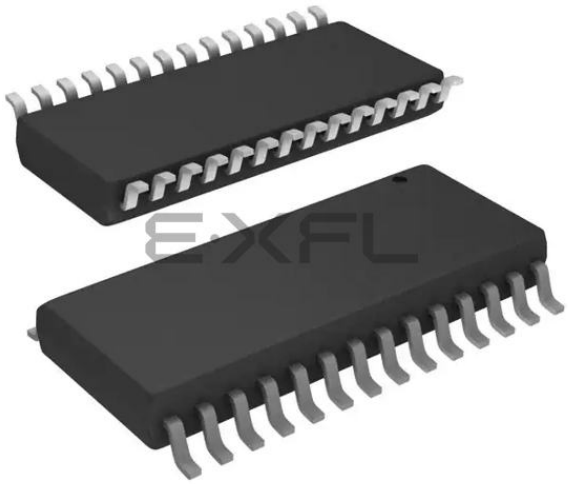

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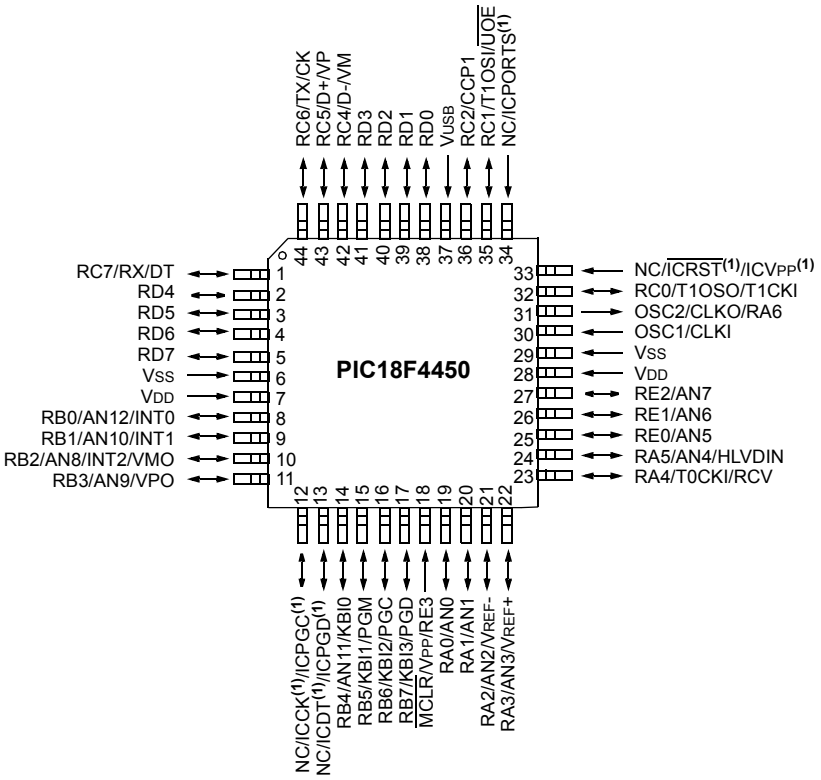
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	UART/USART, USB
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	23
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f2450t-i-so

Pin Diagrams (Continued)

44-Pin TQFP



Note 1: Special ICPORT features are available in select circumstances. For more information, see **Section 18.9 "Special ICPORT Features (Designated Packages Only)"**.

TABLE 2-3: OSCILLATOR CONFIGURATION OPTIONS FOR USB OPERATION (CONTINUED)

Input Oscillator Frequency	PLL Division (PLLDIV2:PLLDIV0)	Clock Mode (FOSC3:FOSC0)	MCU Clock Division (CPUDIV1:CPUDIV0)	Microcontroller Clock Frequency
12 MHz	÷3 (010)	HS, EC, ECIO	None (00)	12 MHz
			÷2 (01)	6 MHz
			÷3 (10)	4 MHz
			÷4 (11)	3 MHz
		HSPLL, ECPLL, ECPIO	÷2 (00)	48 MHz
			÷3 (01)	32 MHz
			÷4 (10)	**24 MHz**
			÷6 (11)	16 MHz
8 MHz	÷2 (001)	HS, EC, ECIO	None (00)	8 MHz
			÷2 (01)	4 MHz
			÷3 (10)	2.67 MHz
			÷4 (11)	2 MHz
		HSPLL, ECPLL, ECPIO	÷2 (00)	48 MHz
			÷3 (01)	32 MHz
			÷4 (10)	**24 MHz**
			÷6 (11)	16 MHz
4 MHz	÷1 (000)	XT, HS, EC, ECIO	None (00)	4 MHz
			÷2 (01)	2 MHz
			÷3 (10)	1.33 MHz
			÷4 (11)	1 MHz
		HSPLL, ECPLL, XTPLL, ECPIO	÷2 (00)	48 MHz
			÷3 (01)	32 MHz
			÷4 (10)	**24 MHz**
			÷6 (11)	16 MHz

Legend: All clock frequencies, except 24 MHz, are exclusively associated with full-speed USB operation (USB clock of 48 MHz). **Bold** is used to highlight clock selections that are compatible with low-speed USB operation (system clock of 24 MHz, USB clock of 6 MHz).

Note 1: Only valid when the USBDIV Configuration bit is cleared.

2.5 Effects of Power-Managed Modes on the Various Clock Sources

When PRI_IDLE mode is selected, the designated primary oscillator continues to run without interruption. For all other power-managed modes, the oscillator using the OSC1 pin is disabled. Unless the USB module is enabled, the OSC1 pin (and OSC2 pin if used by the oscillator) will stop oscillating.

In secondary clock modes (SEC_RUN and SEC_IDLE), the Timer1 oscillator is operating and providing the device clock. The Timer1 oscillator may also run in all power-managed modes if required to clock Timer1.

In internal oscillator modes (RC_RUN and RC_IDLE), the internal oscillator provides the device clock source. The 31 kHz INTRC output can be used directly to provide the clock and may be enabled to support various special features regardless of the power-managed mode (see **Section 18.2 "Watchdog Timer (WDT)"**, **Section 18.3 "Two-Speed Start-up"** and **Section 18.4 "Fail-Safe Clock Monitor"** for more information on WDT, Fail-Safe Clock Monitor and Two-Speed Start-up).

Regardless of the Run or Idle mode selected, the USB clock source will continue to operate. If the device is operating from a crystal or resonator-based oscillator, that oscillator will continue to clock the USB module. The core and all other modules will switch to the new clock source.

If the Sleep mode is selected, all clock sources are stopped. Since all the transistor switching currents have been stopped, Sleep mode achieves the lowest current consumption of the device (only leakage currents).

Sleep mode should never be invoked while the USB module is operating and connected. The only exception is when the device has been issued a "Suspend" command over the USB. Once the module has suspended operation and shifted to a low-power state, the microcontroller may be safely put into Sleep mode.

Enabling any on-chip feature that will operate during Sleep will increase the current consumed during Sleep. The INTRC is required to support WDT operation. The Timer1 oscillator may be operating to support a Real-Time Clock. Other features may be operating that do not require a device clock source (i.e., PSP, INTx pins and others). Peripherals that may add significant current consumption are listed in **Section 21.2 "DC Characteristics: Power-Down and Supply Current"**.

2.6 Power-up Delays

Power-up delays are controlled by two timers, so that no external Reset circuitry is required for most applications. The delays ensure that the device is kept in Reset until the device power supply is stable under normal circumstances and the primary clock is operating and stable. For additional information on power-up delays, see **Section 4.5 "Device Reset Timers"**.

The first timer is the Power-up Timer (PWRT), which provides a fixed delay on power-up (parameter 33, Table 21-10). It is enabled by clearing (= 0) the $\overline{\text{PWRTEN}}$ Configuration bit.

The second timer is the Oscillator Start-up Timer (OST), intended to keep the chip in Reset until the crystal oscillator is stable (XT and HS modes). The OST does this by counting 1024 oscillator cycles before allowing the oscillator to clock the device.

When the HSPLL Oscillator mode is selected, the device is kept in Reset for an additional 2 ms following the HS mode OST delay, so the PLL can lock to the incoming clock frequency.

There is a delay of interval, T_{CSD} (parameter 38, Table 21-10), following POR, while the controller becomes ready to execute instructions. This delay runs concurrently with any other delays. This may be the only delay that occurs when any of the EC or internal oscillator modes are used as the primary clock source.

TABLE 2-4: OSC1 AND OSC2 PIN STATES IN SLEEP MODE

Oscillator Mode	OSC1 Pin	OSC2 Pin
INTCKO	Floating, pulled by external clock	At logic low (clock/4 output)
INTIO	Floating, pulled by external clock	Configured as PORTA, bit 6
ECIO, ECPIO	Floating, pulled by external clock	Configured as PORTA, bit 6
EC	Floating, pulled by external clock	At logic low (clock/4 output)
XT and HS	Feedback inverter disabled at quiescent voltage level	Feedback inverter disabled at quiescent voltage level

Note: See Table 4-2 in **Section 4.0 "Reset"** for time-outs due to Sleep and $\overline{\text{MCLR}}$ Reset.

3.3 Sleep Mode

The power-managed Sleep mode in the PIC18F2450/4450 devices is identical to the legacy Sleep mode offered in all other PIC microcontrollers. It is entered by clearing the IDLEN bit (the default state on device Reset) and executing the SLEEP instruction. This shuts down the selected oscillator (Figure 3-5). All clock source status bits are cleared.

Entering the Sleep mode from any other mode does not require a clock switch. This is because no clocks are needed once the controller has entered Sleep. If the WDT is selected, the INTRC source will continue to operate. If the Timer1 oscillator is enabled, it will also continue to run.

When a wake event occurs in Sleep mode (by interrupt, Reset or WDT time-out), the device will not be clocked until the clock source selected by the SCS1:SCS0 bits becomes ready (see Figure 3-6), or it will be clocked from the internal oscillator if either the Two-Speed Start-up or the Fail-Safe Clock Monitor are enabled (see **Section 18.0 "Special Features of the CPU"**). In either case, the OSTS bit is set when the primary clock is providing the device clocks. The IDLEN and SCS bits are not affected by the wake-up.

3.4 Idle Modes

The Idle modes allow the controller's CPU to be selectively shut down while the peripherals continue to operate. Selecting a particular Idle mode allows users to further manage power consumption.

If the IDLEN bit is set to '1' when a SLEEP instruction is executed, the peripherals will be clocked from the clock source selected using the SCS1:SCS0 bits; however, the CPU will not be clocked. The clock source status bits are not affected. Setting IDLEN and executing a SLEEP instruction provides a quick method of switching from a given Run mode to its corresponding Idle mode.

If the WDT is selected, the INTRC source will continue to operate. If the Timer1 oscillator is enabled, it will also continue to run.

Since the CPU is not executing instructions, the only exits from any of the Idle modes are by interrupt, WDT time-out or a Reset. When a wake event occurs, CPU execution is delayed by an interval of TCSD (parameter 38, Table 21-10) while it becomes ready to execute code. When the CPU begins executing code, it resumes with the same clock source for the current Idle mode. For example, when waking from RC_IDLE mode, the internal oscillator will clock the CPU and peripherals (in other words, RC_RUN mode). The IDLEN and SCS bits are not affected by the wake-up.

While in any Idle mode or Sleep mode, a WDT time-out will result in a WDT wake-up to the Run mode currently specified by the SCS1:SCS0 bits.

FIGURE 3-5: TRANSITION TIMING FOR ENTRY TO SLEEP MODE

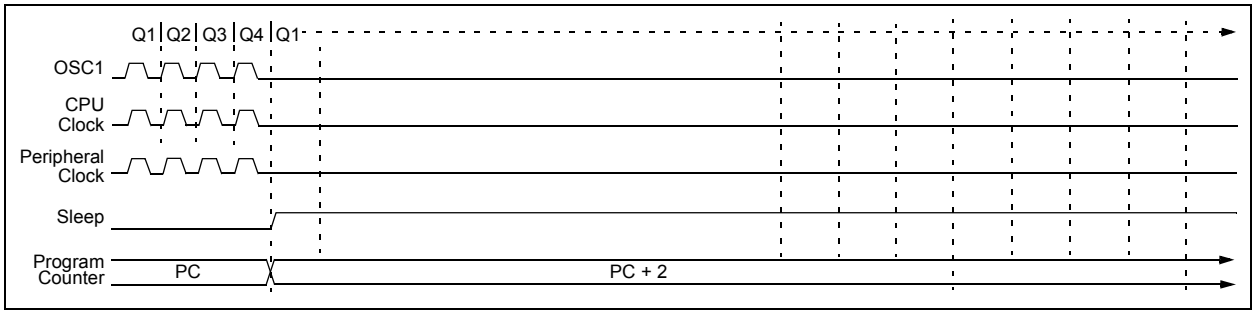
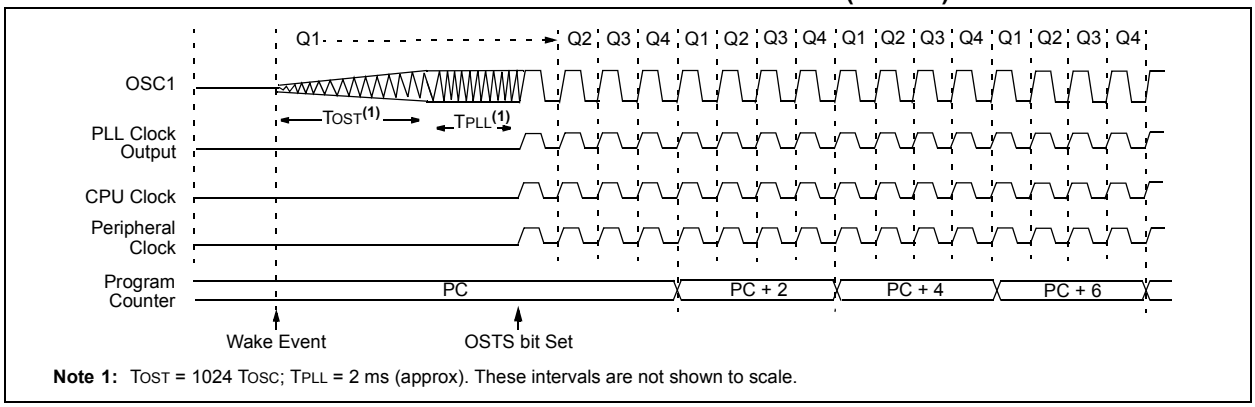


FIGURE 3-6: TRANSITION TIMING FOR WAKE FROM SLEEP (HSPLL)



Note 1: TOST = 1024 TOSC; TPLL = 2 ms (approx). These intervals are not shown to scale.

FIGURE 4-3: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO V_{DD}, V_{DD} RISE < T_{PWRT})

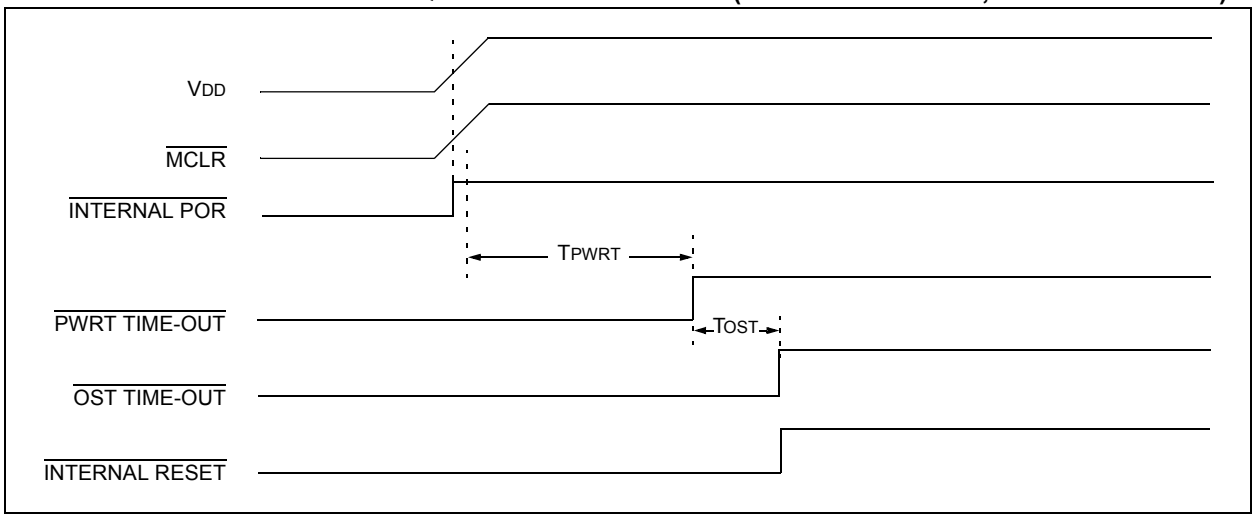


FIGURE 4-4: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 1

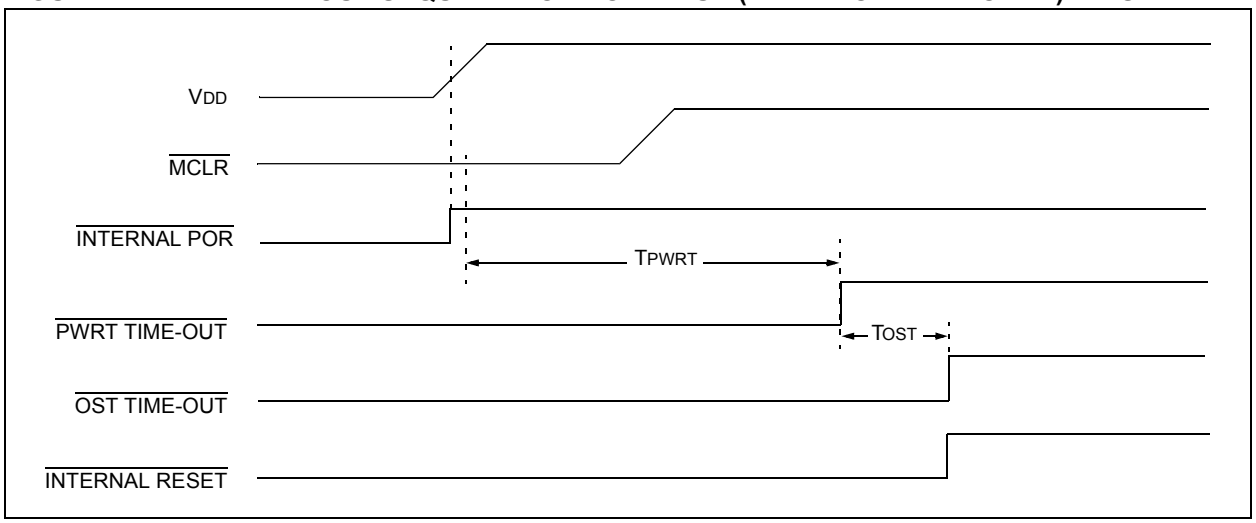


FIGURE 4-5: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 2

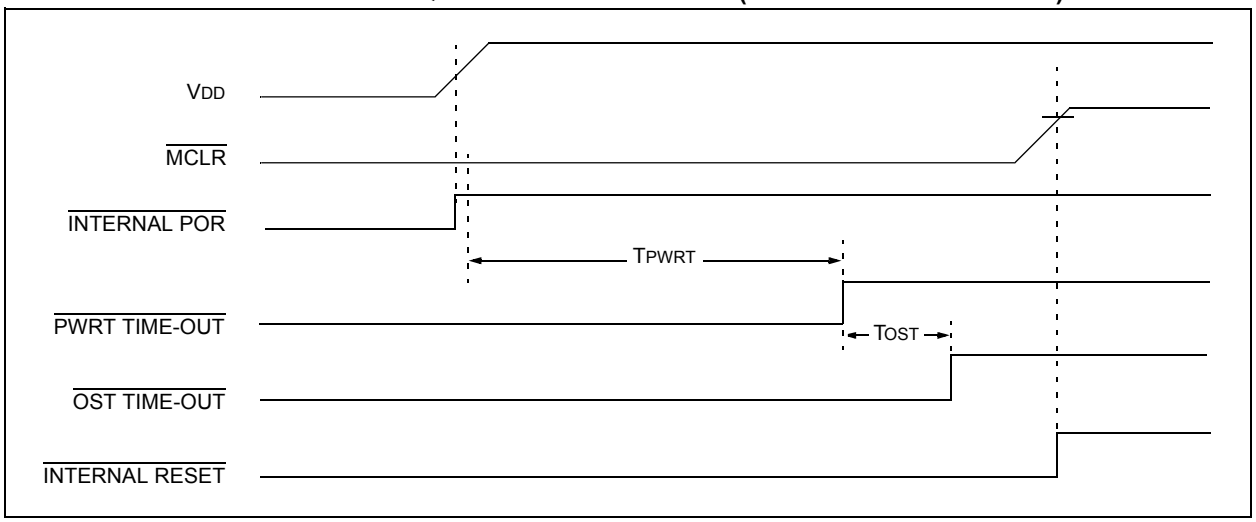


TABLE 4-4: INITIALIZATION CONDITIONS FOR ALL REGISTERS (CONTINUED)

Register	Applicable Devices		Power-on Reset, Brown-out Reset	$\overline{\text{MCLR}}$ Resets, WDT Reset, RESET Instruction, Stack Resets	Wake-up via WDT or Interrupt
UEP9	2450	4450	---0 0000	---0 0000	---u uuuu
UEP8	2450	4450	---0 0000	---0 0000	---u uuuu
UEP7	2450	4450	---0 0000	---0 0000	---u uuuu
UEP6	2450	4450	---0 0000	---0 0000	---u uuuu
UEP5	2450	4450	---0 0000	---0 0000	---u uuuu
UEP4	2450	4450	---0 0000	---0 0000	---u uuuu
UEP3	2450	4450	---0 0000	---0 0000	---u uuuu
UEP2	2450	4450	---0 0000	---0 0000	---u uuuu
UEP1	2450	4450	---0 0000	---0 0000	---u uuuu
UEP0	2450	4450	---0 0000	---0 0000	---u uuuu
UCFG	2450	4450	00-0 0000	00-0 0000	uu-u uuuu
UADDR	2450	4450	-000 0000	-000 0000	-uuu uuuu
UCON	2450	4450	-0x0 000-	-0x0 000-	-uuu uuu-
USTAT	2450	4450	-xxx xxx-	-xxx xxx-	-uuu uuu-
UEIE	2450	4450	0--0 0000	0--0 0000	u--u uuuu
UEIR	2450	4450	0--0 0000	0--0 0000	u--u uuuu
UIE	2450	4450	-000 0000	-000 0000	-uuu uuuu
UIR	2450	4450	-000 0000	-000 0000	-uuu uuuu
UFRMH	2450	4450	---- -xxx	---- -xxx	---- -uuu
UFRML	2450	4450	xxxx xxxx	xxxx xxxx	uuuu uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition. Shaded cells indicate conditions do not apply for the designated device.

Note 1: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the TOSU, TOSH and TOSL are updated with the current value of the PC. The STKPTR is modified to point to the next location in the hardware stack.

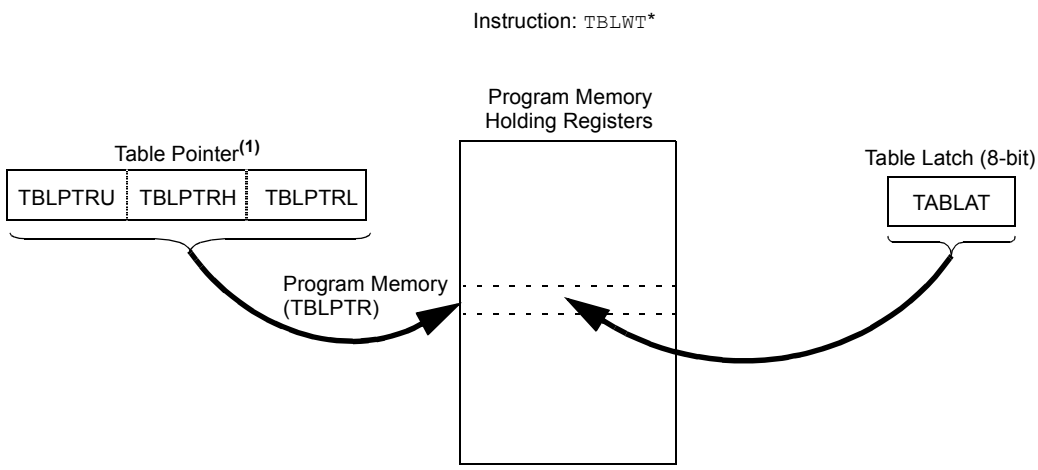
2: One or more bits in the INTCONx or PIRx registers will be affected (to cause wake-up).

3: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).

4: See Table 4-3 for Reset value for specific condition.

5: PORTA<6>, LATA<6> and TRISA<6> are enabled depending on the oscillator mode selected. When not enabled as PORTA pins, they are disabled and read '0'.

FIGURE 6-2: TABLE WRITE OPERATION



Note 1: Table Pointer actually points to one of 16 holding registers, the address of which is determined by TBLPTRL<3:0>. The process for physically writing data to the program memory array is discussed in **Section 6.5 "Writing to Flash Program Memory"**.

6.2 Control Registers

Several control registers are used in conjunction with the TBLRD and TBLWT instructions. These include the:

- EECON1 register
- EECON2 register
- TABLAT register
- TBLPTR registers

6.2.1 EECON1 AND EECON2 REGISTERS

The EECON1 register (Register 6-1) is the control register for memory accesses. The EECON2 register is not a physical register; it is used exclusively in the memory write and erase sequences. Reading EECON2 will read all '0's.

The CFGS control bit determines if the access will be to the Configuration/Calibration registers or to program memory.

The FREE bit, when set, will allow a program memory erase operation. When FREE is set, the erase operation is initiated on the next WR command. When FREE is clear, only writes are enabled.

The WREN bit, when set, will allow a write operation. On power-up, the WREN bit is clear. The WRERR bit is set in hardware when the WREN bit is set and cleared when the internal programming timer expires and the write operation is complete.

Note:	During normal operation, the WRERR is read as '1'. This can indicate that a write operation was prematurely terminated by a Reset or a write operation was attempted improperly.

The WR control bit initiates write operations. The bit cannot be cleared, only set, in software; it is cleared in hardware at the completion of the write operation.

TABLE 9-5: PORTC I/O SUMMARY

Pin	Function	TRIS Setting	I/O	I/O Type	Description
RC0/T1OSO/ T1CKI	RC0	0	OUT	DIG	LATC<0> data output.
		1	IN	ST	PORTC<0> data input.
	T1OSO	x	OUT	ANA	Timer1 oscillator output; enabled when Timer1 oscillator enabled. Disables digital I/O.
	T1CKI	1	IN	ST	Timer1 counter input.
RC1/T1OSI/ $\overline{UOE}$	RC1	0	OUT	DIG	LATC<1> data output.
		1	IN	ST	PORTC<1> data input.
	T1OSI	x	IN	ANA	Timer1 oscillator input; enabled when Timer1 oscillator enabled. Disables digital I/O.
	$\overline{UOE}$	0	OUT	DIG	External USB transceiver $\overline{OE}$ output.
RC2/CCP1	RC2	0	OUT	DIG	LATC<2> data output.
		1	IN	ST	PORTC<2> data input.
	CCP1	0	OUT	DIG	CCP1 Compare and PWM output; takes priority over port data.
		1	IN	ST	CCP1 Capture input.
RC4/D-/VM	RC4	—(1)	IN	TTL	PORTC<4> data input; disabled when USB module or on-chip transceiver is enabled.
	D-	—(1)	OUT	XCVR	USB bus differential minus line output (internal transceiver).
		—(1)	IN	XCVR	USB bus differential minus line input (internal transceiver).
	VM	—(1)	IN	TTL	External USB transceiver VM input.
RC5/D+/VP	RC5	—(1)	IN	TTL	PORTC<5> data input; disabled when USB module or on-chip transceiver is enabled.
	D+	—(1)	OUT	XCVR	USB bus differential plus line output (internal transceiver).
		—(1)	IN	XCVR	USB bus differential plus line input (internal transceiver).
	VP	—(1)	IN	TTL	External USB transceiver VP input.
RC6/TX/CK	RC6	0	OUT	DIG	LATC<6> data output.
		1	IN	ST	PORTC<6> data input.
	TX	0	OUT	DIG	Asynchronous serial transmit data output (EUSART module); takes priority over port data. User must configure as output.
	CK	0	OUT	DIG	Synchronous serial clock output (EUSART module); takes priority over port data.
		1	IN	ST	Synchronous serial clock input (EUSART module).
RC7/RX/DT	RC7	0	OUT	DIG	LATC<7> data output.
		1	IN	ST	PORTC<7> data input.
	RX	1	IN	ST	Asynchronous serial receive data input (EUSART module).
	DT	1	OUT	DIG	Synchronous serial data output (EUSART module).
		1	IN	ST	Synchronous serial data input (EUSART module). User must configure as an input.

Legend: OUT = Output, IN = Input, ANA = Analog Signal, DIG = Digital Output, ST = Schmitt Buffer Input, TTL = TTL Buffer Input, XCVR = USB Transceiver, x = Don't care (TRIS bit does not affect port direction or is overridden for this option)

Note 1: RC4 and RC5 do not have corresponding TRISC bits. In Port mode, these pins are input only. USB data direction is determined by the USB configuration.

TABLE 9-6: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
PORTC	RC7	RC6	RC5(1)	RC4(1)	—	RC2	RC1	RC0	51
LATC	LATC7	LATC6	—	—	—	LATC2	LATC1	LATC0	51
TRISC	TRISC7	TRISC6	—	—	—	TRISC2	TRISC1	TRISC0	51
UCON	—	PPBRST	SE0	PKTDIS	USBEN	RESUME	SUSPND	—	52

Legend: — = unimplemented, read as '0'. Shaded cells are not used by PORTC.

Note 1: RC5 and RC4 are only available as port pins when the USB module is disabled (UCON<3> = 0).

TABLE 9-9: PORTE I/O SUMMARY

Pin	Function	TRIS Setting	I/O	I/O Type	Description
RE0/AN5	RE0	0	OUT	DIG	LATE<0> data output; not affected by analog input.
		1	IN	ST	PORTE<0> data input; disabled when analog input enabled.
	AN5	1	IN	ANA	A/D input channel 5; default configuration on POR.
RE1/AN6	RE1	0	OUT	DIG	LATE<1> data output; not affected by analog input.
		1	IN	ST	PORTE<1> data input; disabled when analog input enabled.
	AN6	1	IN	ANA	A/D input channel 6; default configuration on POR.
RE2/AN7	RE2	0	OUT	DIG	LATE<2> data output; not affected by analog input.
		1	IN	ST	PORTE<2> data input; disabled when analog input enabled.
	AN7	1	IN	ANA	A/D input channel 7; default configuration on POR.
$\overline{MCLR}$/VPP/ RE3	$\overline{MCLR}$	—(1)	IN	ST	External Master Clear input; enabled when MCLRE Configuration bit is set.
	VPP	—(1)	IN	ANA	High-voltage detection, used for ICSP™ mode entry detection. Always available regardless of pin mode.
	RE3	—(1)	IN	ST	PORTE<3> data input; enabled when MCLRE Configuration bit is clear.

Legend: OUT = Output, IN = Input, ANA = Analog Signal, DIG = Digital Output, ST = Schmitt Buffer Input.

Note 1: RE3 does not have a corresponding TRISE<3> bit. This pin is always an input regardless of mode.

TABLE 9-10: SUMMARY OF REGISTERS ASSOCIATED WITH PORTE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
PORTE	—	—	—	—	RE3(1,2)	RE2(3)	RE1(3)	RE0(3)	51
LATE(3)	—	—	—	—	—	LATE2	LATE1	LATE0	51
TRISE(3)	—	—	—	—	—	TRISE2	TRISE1	TRISE0	51
ADCON1	—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	50

Legend: — = unimplemented, read as '0'

Note 1: Implemented only when Master Clear functionality is disabled (MCLRE Configuration bit = 0); otherwise, read as '0'.

2: RE3 is the only PORTE bit implemented on both 28-pin and 40/44-pin devices. All other bits are implemented only when PORTE is implemented (i.e., 40/44-pin devices).

3: These registers and/or bits are unimplemented on 28-pin devices.

NOTES:

14.2.4 USB ENDPOINT CONTROL

Each of the 16 possible bidirectional endpoints has its own independent control register, UEPn (where 'n' represents the endpoint number). Each register has an identical complement of control bits. The prototype is shown in Register 14-4.

The EPHSHK bit (UEPn<4>) controls handshaking for the endpoint; setting this bit enables USB handshaking. Typically, this bit is always set except when using isochronous endpoints.

The EPCONDIS bit (UEPn<3>) is used to enable or disable USB control operations (SETUP) through the endpoint. Clearing this bit enables SETUP transactions. Note that the corresponding EPINEN and EPOUTEN bits must be set to enable IN and OUT transactions. For Endpoint 0, this bit should always be cleared since the USB specifications identify Endpoint 0 as the default control endpoint.

The EPOUTEN bit (UEPn<2>) is used to enable or disable USB OUT transactions from the host. Setting this bit enables OUT transactions. Similarly, the EPINEN bit (UEPn<1>) enables or disables USB IN transactions from the host.

The EPSTALL bit (UEPn<0>) is used to indicate a STALL condition for the endpoint. If a STALL is issued on a particular endpoint, the EPSTALL bit for that endpoint pair will be set by the SIE. This bit remains set until it is cleared through firmware, or until the SIE is reset.

REGISTER 14-4: UEPn: USB ENDPOINT n CONTROL REGISTER (UEP0 THROUGH UEP15)

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	EPHSHK	EPCONDIS	EPOUTEN	EPINEN	EPSTALL(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **EPHSHK:** Endpoint Handshake Enable bit
1 = Endpoint handshake enabled
0 = Endpoint handshake disabled (typically used for isochronous endpoints)

bit 3 **EPCONDIS:** Bidirectional Endpoint Control bit
If EPOUTEN = 1 and EPINEN = 1:
1 = Disable Endpoint n from control transfers; only IN and OUT transfers allowed
0 = Enable Endpoint n for control (SETUP) transfers; IN and OUT transfers also allowed

bit 2 **EPOUTEN:** Endpoint Output Enable bit
1 = Endpoint n output enabled
0 = Endpoint n output disabled

bit 1 **EPINEN:** Endpoint Input Enable bit
1 = Endpoint n input enabled
0 = Endpoint n input disabled

bit 0 **EPSTALL:** Endpoint Stall Indicator bit
1 = Endpoint n has issued one or more STALL packets
0 = Endpoint n has not issued any STALL packets

BTFSC **Bit Test File, Skip if Clear**

Syntax: BTFSC f, b {,a}

Operands: $0 \le f \le 255$
$0 \le b \le 7$
$a \in [0,1]$

Operation: skip if (f<b>) = 0

Status Affected: None

Encoding:

1011	bbba	ffff	ffff

Description: If bit 'b' in register 'f' is '0', then the next instruction is skipped. If bit 'b' is '0', then the next instruction fetched during the current instruction execution is discarded and a NOP is executed instead, making this a two-cycle instruction.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default).
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh).
See **Section 19.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    BTFSC   FLAG, 1, 0
FALSE   :
TRUE    :
```

Before Instruction
PC = address (HERE)
After Instruction
If FLAG<1> = 0;
PC = address (TRUE)
If FLAG<1> = 1;
PC = address (FALSE)

BTFSS **Bit Test File, Skip if Set**

Syntax: BTFSS f, b {,a}

Operands: $0 \le f \le 255$
$0 \le b < 7$
$a \in [0,1]$

Operation: skip if (f<b>) = 1

Status Affected: None

Encoding:

1010	bbba	ffff	ffff

Description: If bit 'b' in register 'f' is '1', then the next instruction is skipped. If bit 'b' is '1', then the next instruction fetched during the current instruction execution is discarded and a NOP is executed instead, making this a two-cycle instruction.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank (default).
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh).
See **Section 19.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    BTFSS   FLAG, 1, 0
FALSE   :
TRUE    :
```

Before Instruction
PC = address (HERE)
After Instruction
If FLAG<1> = 0;
PC = address (FALSE)
If FLAG<1> = 1;
PC = address (TRUE)

21.2 DC Characteristics: Power-Down and Supply Current PIC18F2450/4450 (Industrial) PIC18LF2450/4450 (Industrial) (Continued)

PIC18LF2450/4450 (Industrial)		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F2450/4450 (Industrial)		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2)						
	PIC18LF2450/4450	200	500	µA	-40°C	VDD = 2.0V	FOSC = 1 MHz (**PRI_RUN**, EC oscillator)
		200	500	µA	+25°C		
		200	500	µA	+85°C		
	PIC18LF2450/4450	500	650	µA	-40°C	VDD = 3.0V	
		400	650	µA	+25°C		
		360	650	µA	+85°C		
	All devices	1.0	1.6	mA	-40°C	VDD = 5.0V	
		0.9	1.5	mA	+25°C		
		0.8	1.4	mA	+85°C		
	PIC18LF2450/4450	0.53	2.0	mA	-40°C	VDD = 2.0V	FOSC = 4 MHz (**PRI_RUN**, EC oscillator)
		0.53	2.0	mA	+25°C		
		0.55	2.0	mA	+85°C		
	PIC18LF2450/4450	1.0	3.0	mA	-40°C	VDD = 3.0V	
		0.9	3.0	mA	+25°C		
		0.9	3.0	mA	+85°C		
	All devices	2.0	6.0	mA	-40°C	VDD = 5.0V	
		1.9	6.0	mA	+25°C		
		1.8	6.0	mA	+85°C		
	All devices	11.0	35	mA	-40°C	VDD = 4.2V	FOSC = 40 MHz (**PRI_RUN**, EC oscillator)
		11.0	35	mA	+25°C		
		11.3	35	mA	+85°C		
	All devices	14.0	40	mA	-40°C	VDD = 5.0V	
		14.0	40	mA	+25°C		
		14.5	40	mA	+85°C		
	All devices	20	40	mA	-40°C	VDD = 4.2V	FOSC = 48 MHz (**PRI_RUN**, EC oscillator)
		20	40	mA	+25°C		
		20	40	mA	+85°C		
	All devices	25	50	mA	-40°C	VDD = 5.0V	
		25	50	mA	+25°C		
		25	50	mA	+85°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: Standard low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

21.3 DC Characteristics: PIC18F2450/4450 (Industrial) PIC18LF2450/4450 (Industrial) (Continued)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial			
Param No.	**Sym**	**Characteristic**	**Min**	**Max**	**Units**	**Conditions**
	VOL	**Output Low Voltage**				
D080		I/O Ports (except RC4/RC5 in USB mode)	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D083		OSC2/CLKO (EC, ECIO modes)	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
	VOH	**Output High Voltage(3)**				
D090		I/O Ports (except RC4/RC5 in USB mode)	VDD – 0.7	—	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D092		OSC2/CLKO (EC, ECIO, ECPIO modes)	VDD – 0.7	—	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
		Capacitive Loading Specs on Output Pins				
D100(4)	COSC2	OSC2 pin	—	15	pF	In XT and HS modes when external clock is used to drive OSC1
D101	CIO	All I/O pins and OSC2 (in RC mode)	—	50	pF	To meet the AC Timing Specifications

Note 1: In RC oscillator configuration, the OSC1/CLKI pin is a Schmitt Trigger input. It is not recommended that the PIC® microcontroller be driven with an external clock while in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

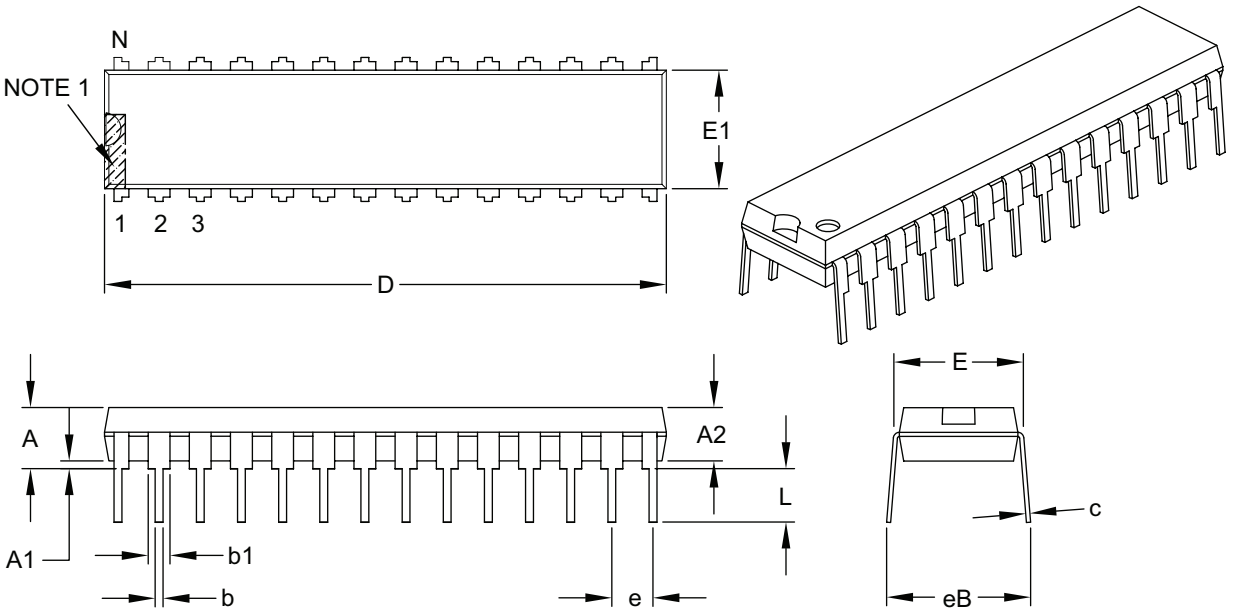
4: Parameter is characterized but not tested.

22.2 Package Details

The following sections give the technical details of the packages.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

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